

Ultra-Conducting Copper (UCC) (Keystone Project #2)

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Oak Ridge National Laboratory

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Annual Merit Review**

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**U.S. DEPARTMENT OF
ENERGY**

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Overview

Timeline

- Start – FY19
- End – FY21
- 25% complete

Budget

- Total project funding
 - DOE share – 100%
- Funding for FY19: \$150K

Barriers

- Meeting DOE ELT 2025 power density & cost targets
- Increasing both the electrical & thermal conductivity of windings to increase efficiency of electric motors (EMs)

Partners

- Southwire, Magnekon, & Chasm
- ORNL team members: Tolga Aytug, Burak Ozpineci, Mina Yoon, Michael McGuire, Andrew Lupini, Tsarafidy Raminosoa, Chengyun Hua, Lydia Skolrood, and Kai Li

Any proposed future work is subject to change based on funding levels

Project Objective and Relevance

- **Overall Objective:**

- Develop a new class of high performance copper (Cu) wires using carbon nanotubes (CNT) that are higher in electrical & thermal conductivity to increase the power density of electric motors while improving the overall efficiency

- **FY19 Objectives:**

- Optimize processing protocols & identify the two most promising scalable approaches for the prototyping of carbon nanomaterial enabled UCC conductors
- Integrate additional Cu/CNT stack(s) on the first Cu/CNT/Cu architecture & investigate their influence on the electrical performance
- Utilize theoretical modelling to understand metal-nanocarbon interface properties for optimized electronic/thermal transport characteristics
- Understand the impact of UCC winding conductivity on traction motors performance

Milestones

Date	Milestones and Go/No-Go Decision	Status
Dec. 2018	<u>Milestone</u> : Optimize processing protocols & produce prototype multilayer Cu/CNT/Cu composites	✓
April 2019	<u>Milestone</u> : Down-select at least one promising processing approach that provides reproducible CNT alignment & performance	✓
June 2019	<u>Milestone</u> : Establish roll-to-roll deposition capability of CNTs on Cu tapes using sonospray technique	On track
Sept. 2019	<u>Go/No-Go decision</u> : Integrate additional Cu/CNT stack(s) on the first Cu/CNT/Cu architecture and determine if these multilayer prototype UCC composites demonstrate improved electrical conductivity	On track

Approach/Strategy

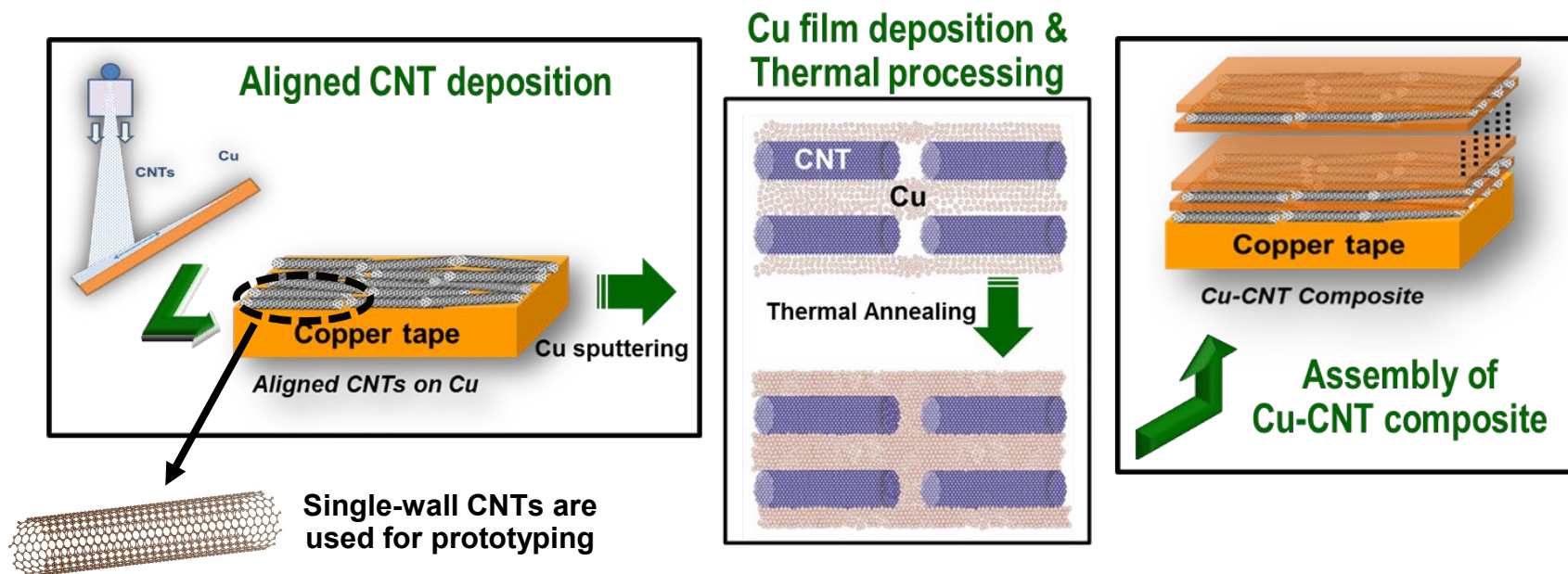
Design an advanced composite material consisting of carbon nanotubes embedded in Cu matrix – Ultra Conductive Copper (UCC)

A better conductor with reduced electrical loss enables:

- Volume/weight reductions ➡ improved power density and specific power
- Higher efficiency (i.e., lower conduction losses)

Process-flow for ORNL-UCCs:

1) CNT deposition; 2) Cu-film deposition/annealing; 3) Cu-CNT multilayer assembly

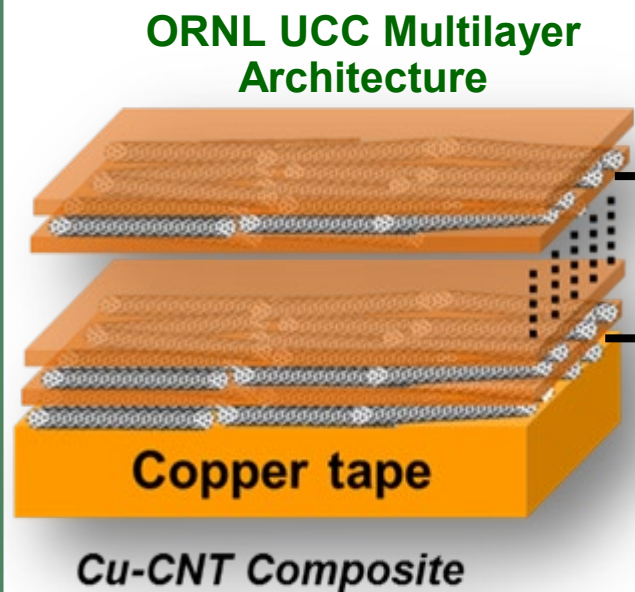


Approach/Strategy

CNTs provide extraordinary electrical, thermal, & mechanical properties compared to Cu

- ➔ ×1.7 higher electrical conductivity (along the tube axis)
- ➔ ×10 higher thermal conductivity (along the tube axis)
- ➔ ×100 current density

	Cu	CNT
Electrical Conductivity	59.6 MS/m	100 MS/m
Thermal Conductivity	400 W/m-K	4000 W/m-K
Current Density	10^6 A/cm ²	10^8 A/cm ²



Process challenges:

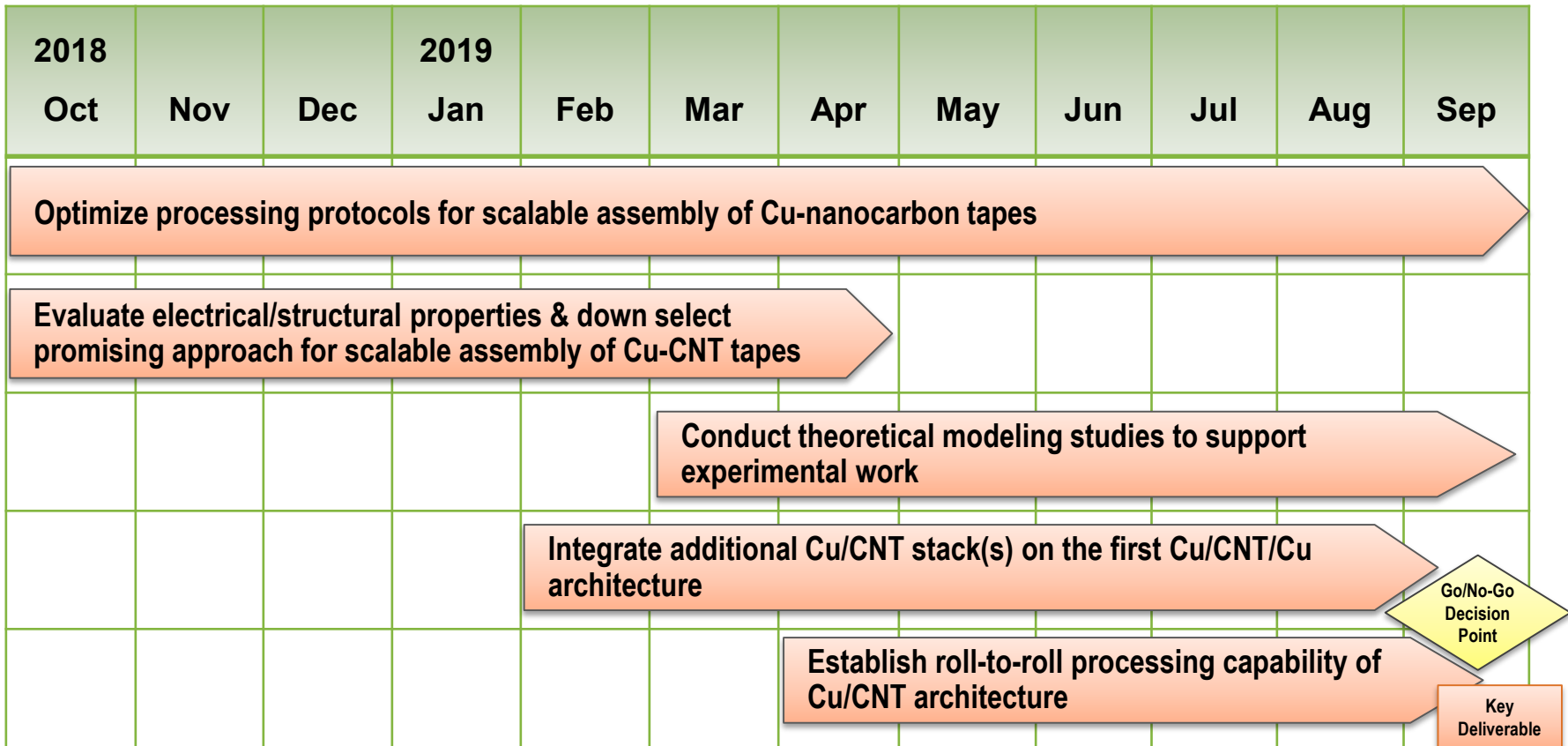
Cu-film (orange layers):

Any voids/porosity from the Cu/CNT matrix needs to be eliminated

CNT-layer:

- CNTs need to be aligned along the tape length (i.e, direction of current)
- Organic processing chemicals (solvent & surfactants) used during processing must be removed from the CNT matrix

Approach FY19 Timeline

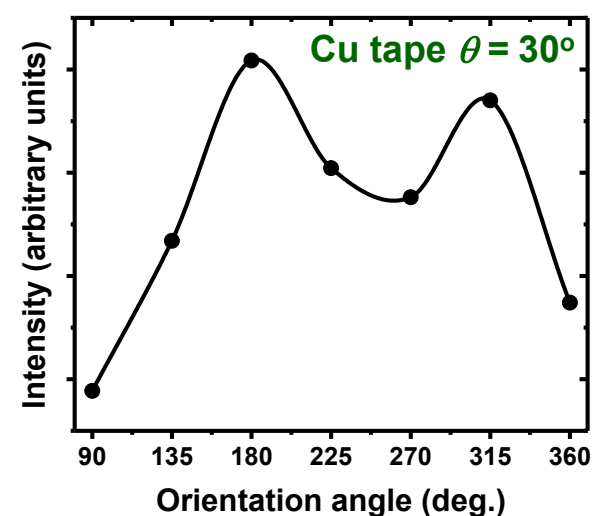
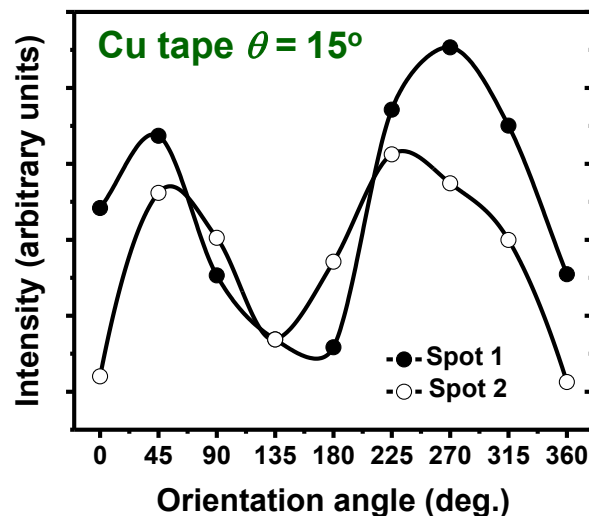
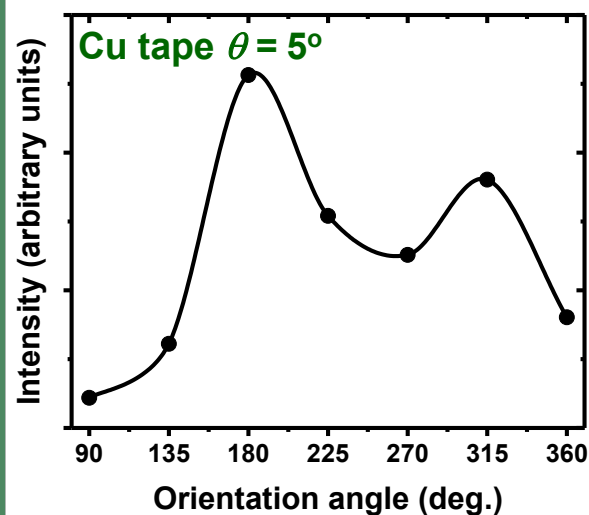
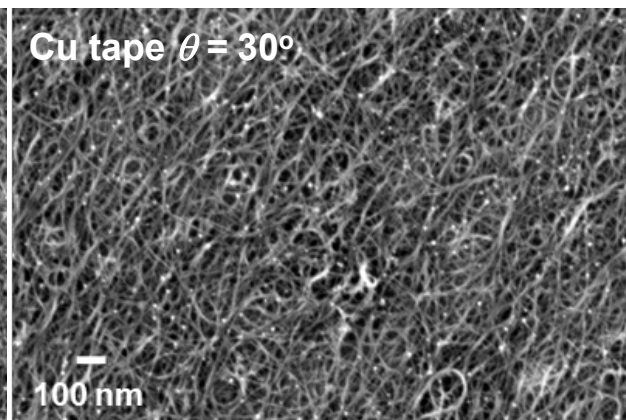
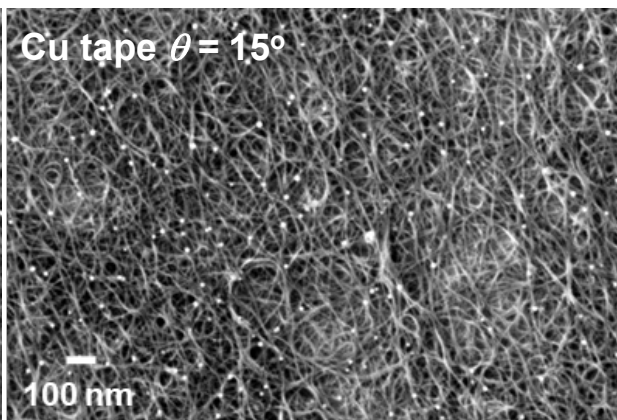
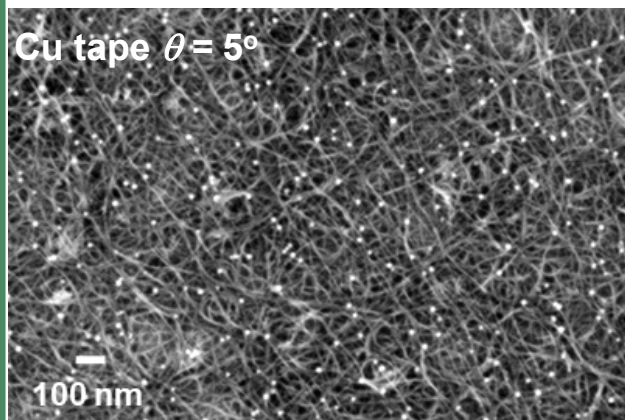
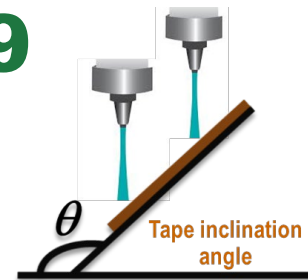


Go/No-Go Decision Point: Integrate additional Cu/CNT stack(s) on the first Cu/CNT/Cu architecture and determine if these multilayer prototype UCC composites demonstrate improved electrical conductivity

Key Deliverable: Sufficient number of Cu-CNT single-/multi- layer specimens for performance evaluation

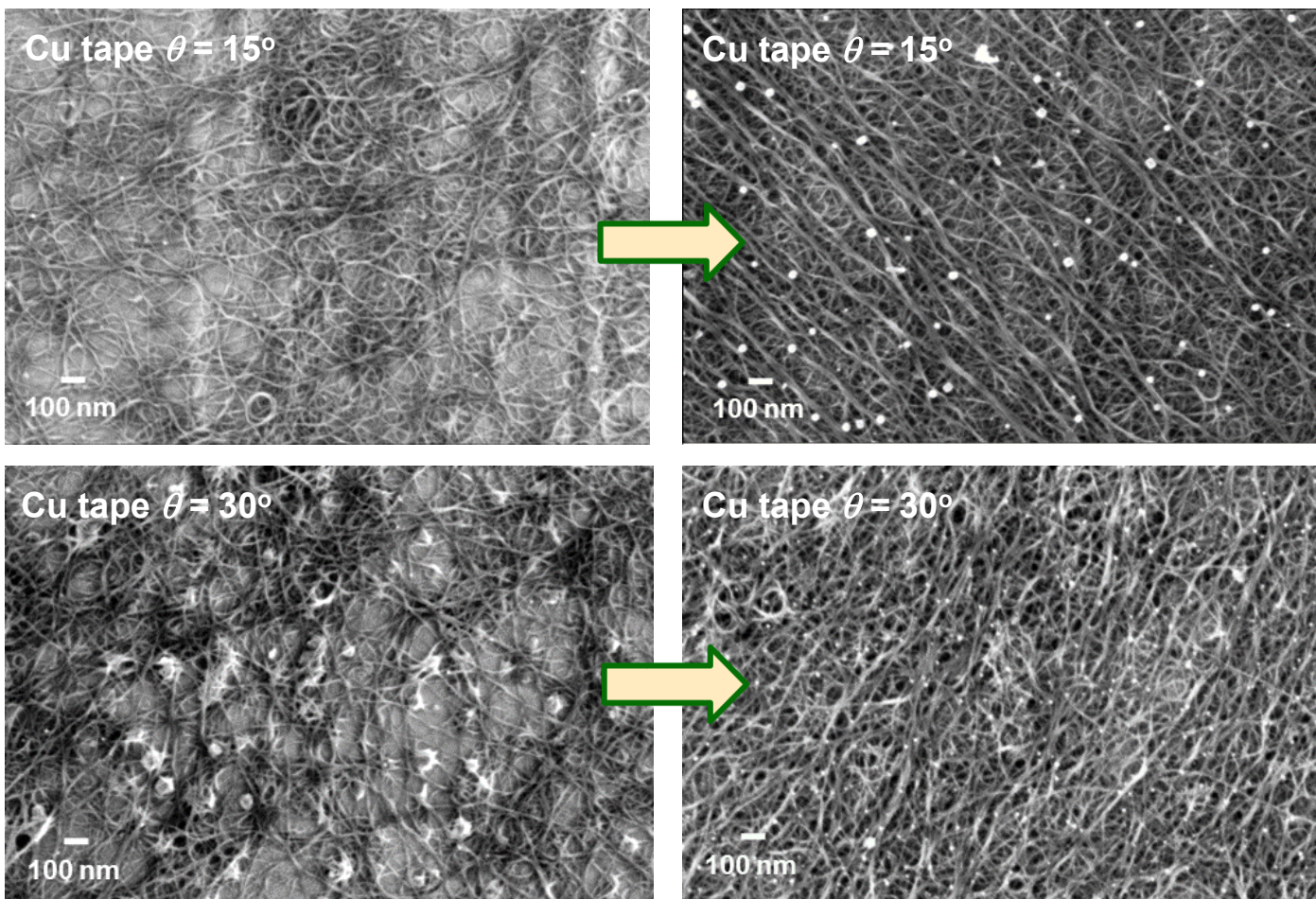
Technical Accomplishments – FY19

Optimize process: Using SEM & polarized Raman spectroscopy confirmed that shear induced alignment of CNTs can occur at all experimentally accessible Cu tape inclination angles during sonospray



Technical Accomplishments – FY19

Optimize process: Established that preferential shear induced alignment along the tape length initiates with increase in CNT amount

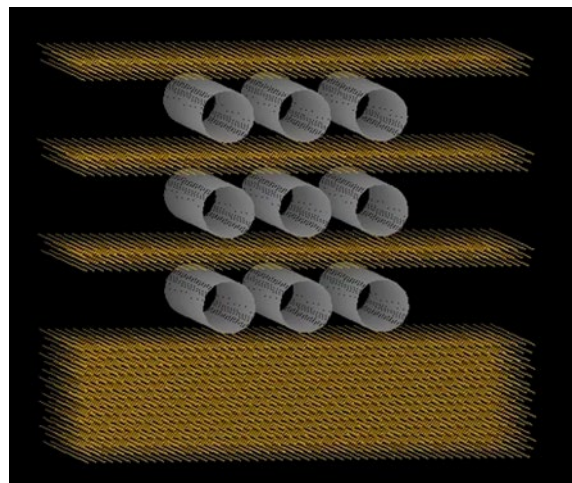


Higher amount of CNT loading on the Cu surface increases shear for alignment parallel to flow-field direction

Technical Accomplishments – FY19

Used theoretical modeling & simulations to optimize materials & process parameters for multilayered UCC assembly

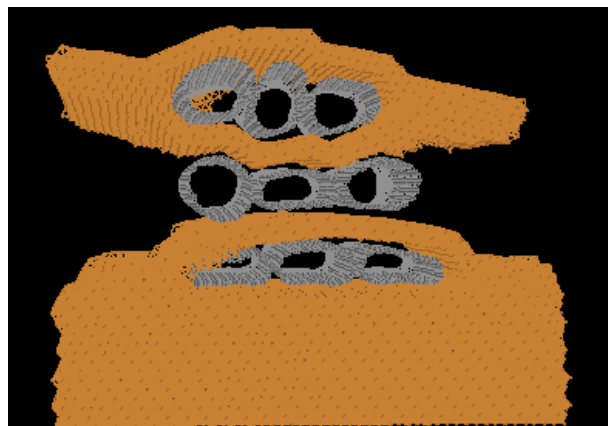
3 Cu/CNT/Cu layer composite



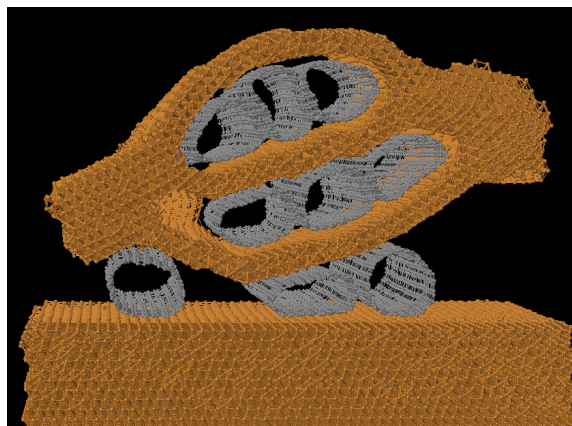
Classical molecular dynamics simulations based on empirical potentials performed to identify the optimum temperature to homogeneously coat CNTs with Cu layers; determined by the competition between diffusion of CNTs on Cu substrate & melting of Cu layers

- ➔ Identified the range of critical temperature (400 °C) where the formation of homogeneously covered Cu/CNT assembly is favorable
- ➔ Simulations showed similar behavior for the 2-layer Cu/CNT/Cu composites

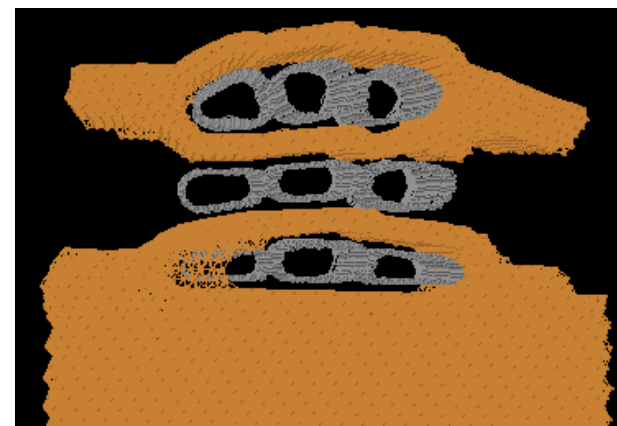
T = 300 °C



T = 400 °C

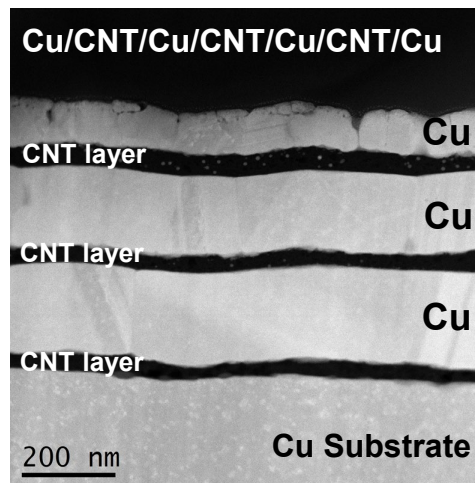
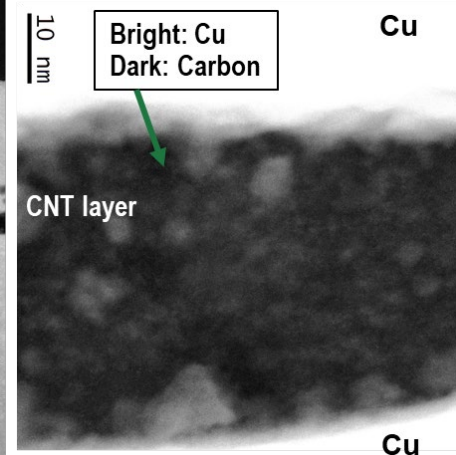
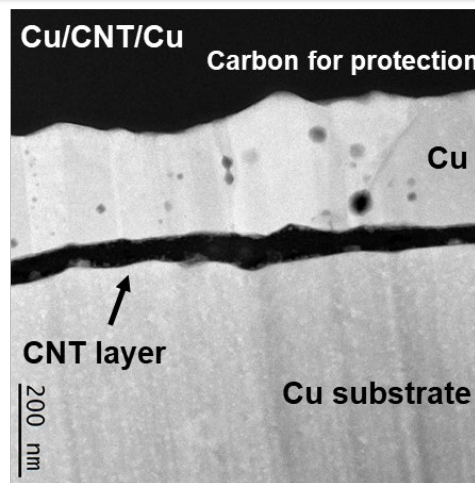
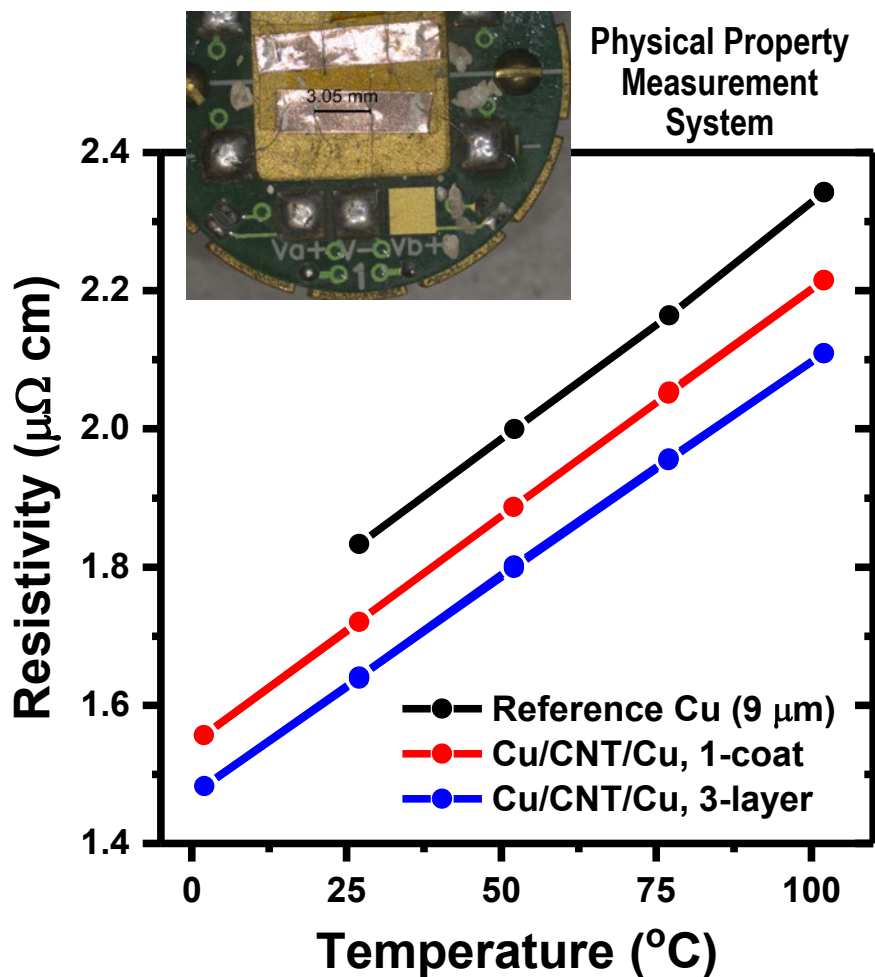


T = 500 °C



Technical Accomplishments – FY19

Integrated additional Cu/CNT stack(s) on the first Cu/CNT/Cu architecture & demonstrated improved conductivity over reference pure Cu for prototype multilayered UCC composites (sonospray samples)



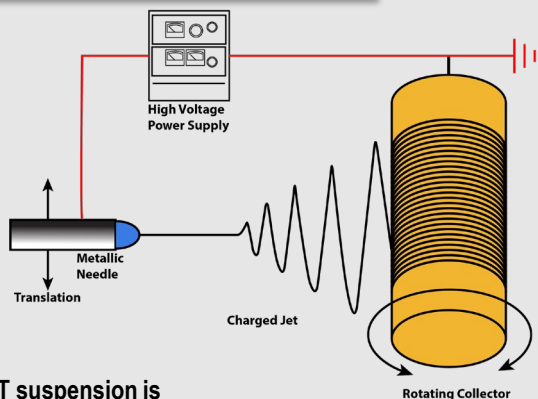
- Evidence of Cu inside the CNT layers
- Relatively homogeneous & dense Cu films on CNT layers
- Any current rendering defects (e.g., voids & pores) throughout the Cu/CNT matrix needs to be eliminated

Decreased resistivity > 10% for multilayer Cu/CNT/Cu (3-stacks) prototype, ($T = 0 - 100^{\circ}\text{C}$)

Technical Accomplishments – FY19

Explored the viability of two new processing techniques & CNT dispersion formulations for deposition on Cu tapes: **1 – Electrospinning**

Electrospin/Electrospray



CNT suspension is extruded from the needle tip at a constant rate under high voltage

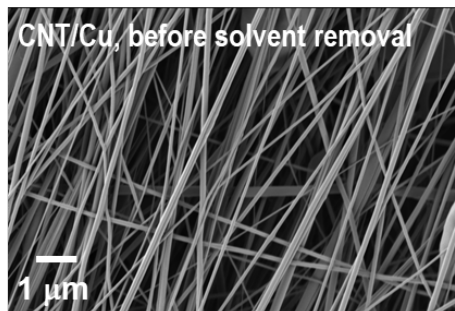
High voltage applied between the syringe & collector induce droplet elongation along deposition direction

CNT/Cu

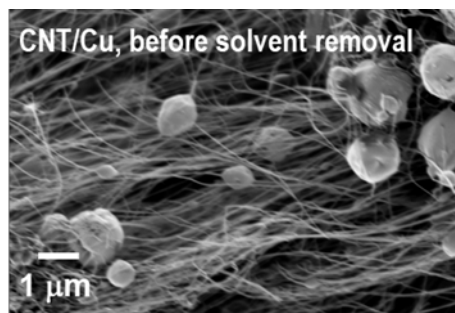
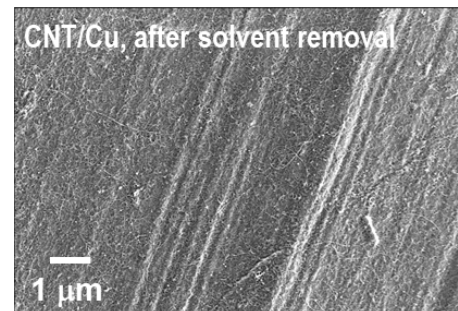


DMF + PVP solution:

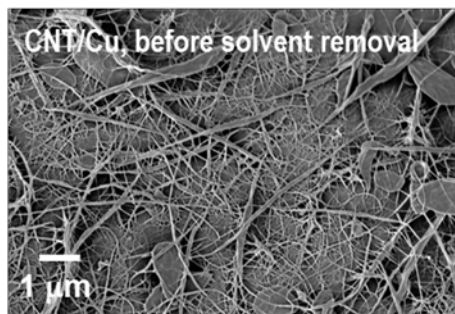
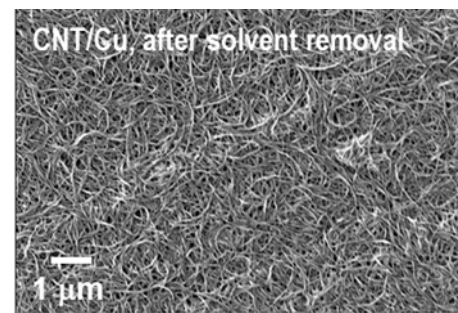
Aligned CNT fibers & uniform CNT coverage on Cu substrate



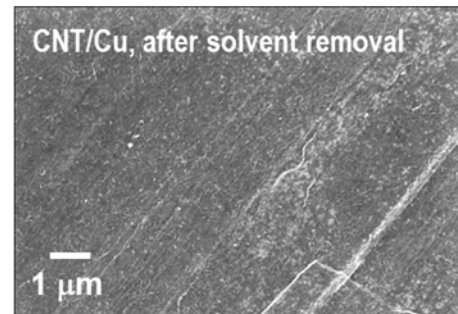
Solvent: Dimethylformamide (DMF) + polyvinyl pyrrolidone (PVP)



Solvent: PVP + ethanol + water

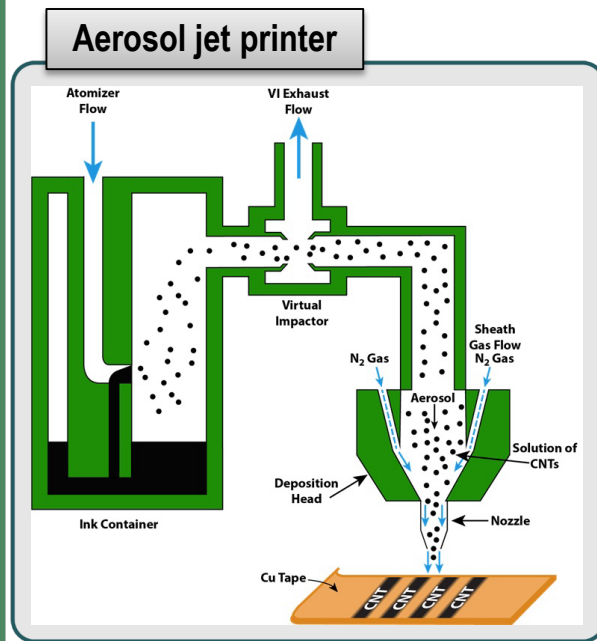


Solvent: DMF

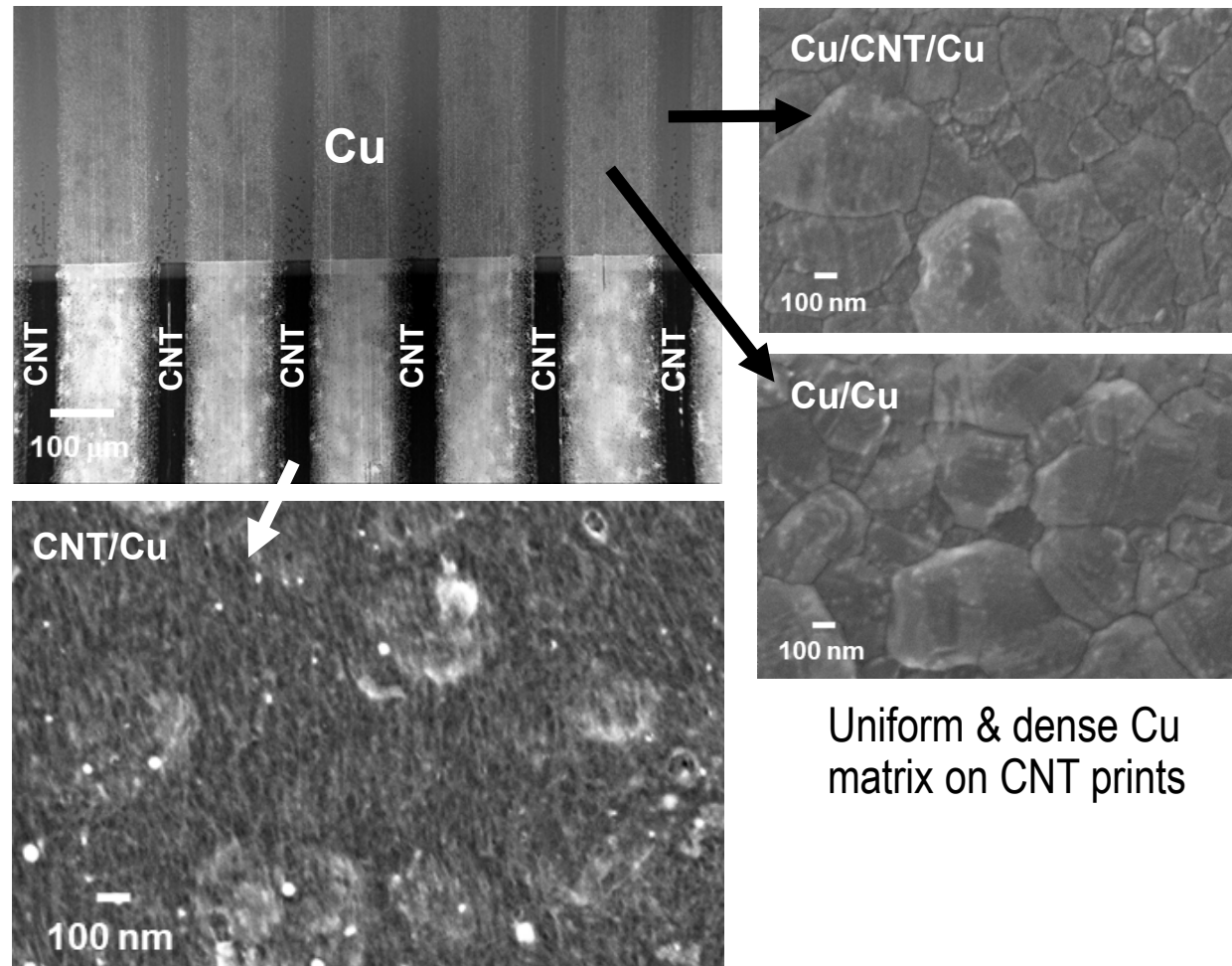


Technical Accomplishments – FY19

Explored the viability of two new processing techniques & CNT formulations for deposition on Cu tapes: **2 – Aerosol Jet Printing**



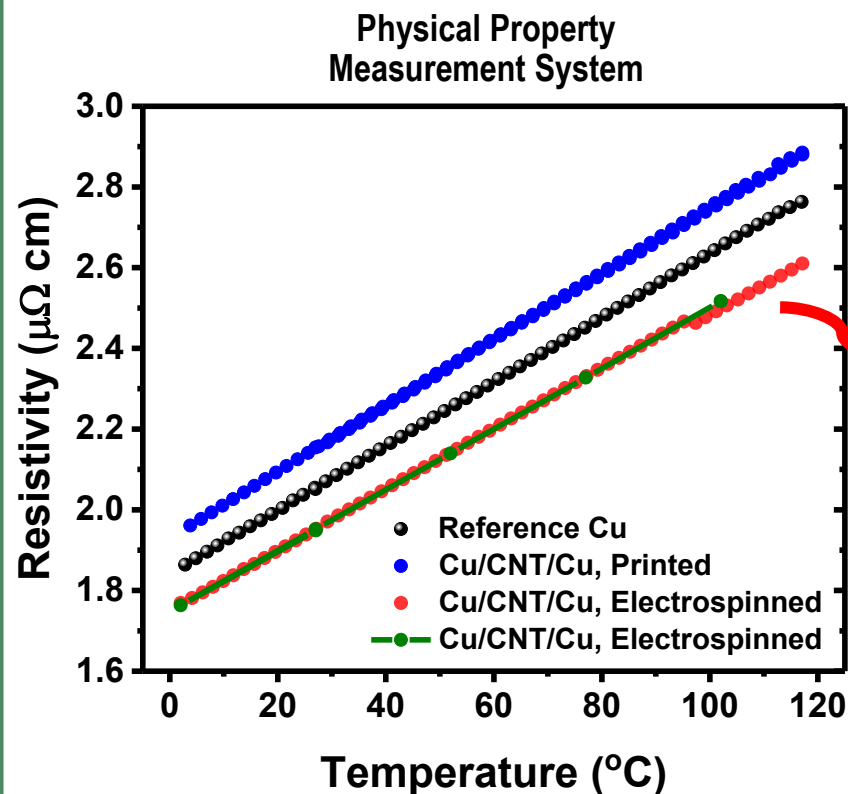
Demonstrated preferential CNT alignment along the tape length with aerosol jet printer



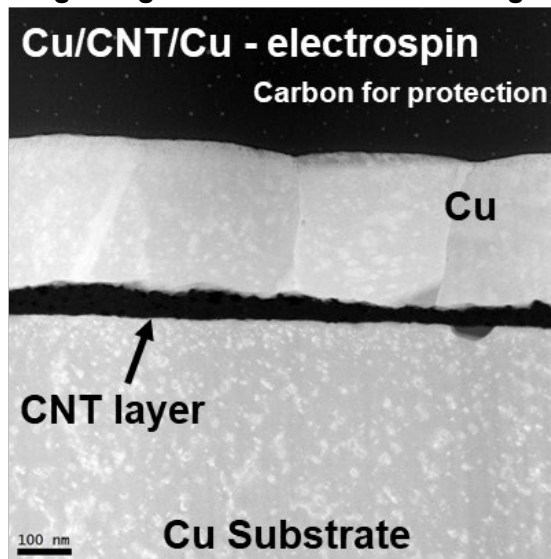
Uniform & dense Cu matrix on CNT prints

Technical Accomplishments – FY19

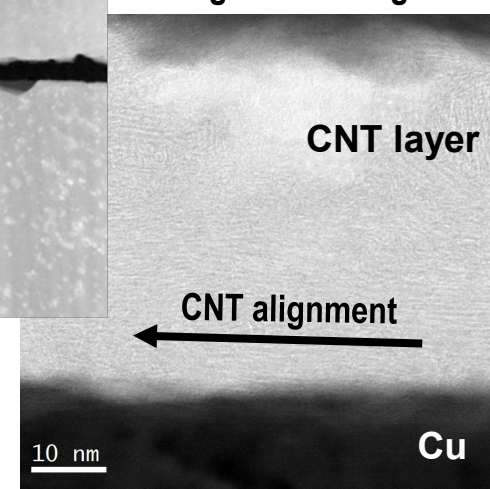
Demonstrated improved conductivity for electrospun single CNT layer UCC prototypes over reference Cu, however conductivity is lower for printed samples



High-angle annular dark field image



Bright field image

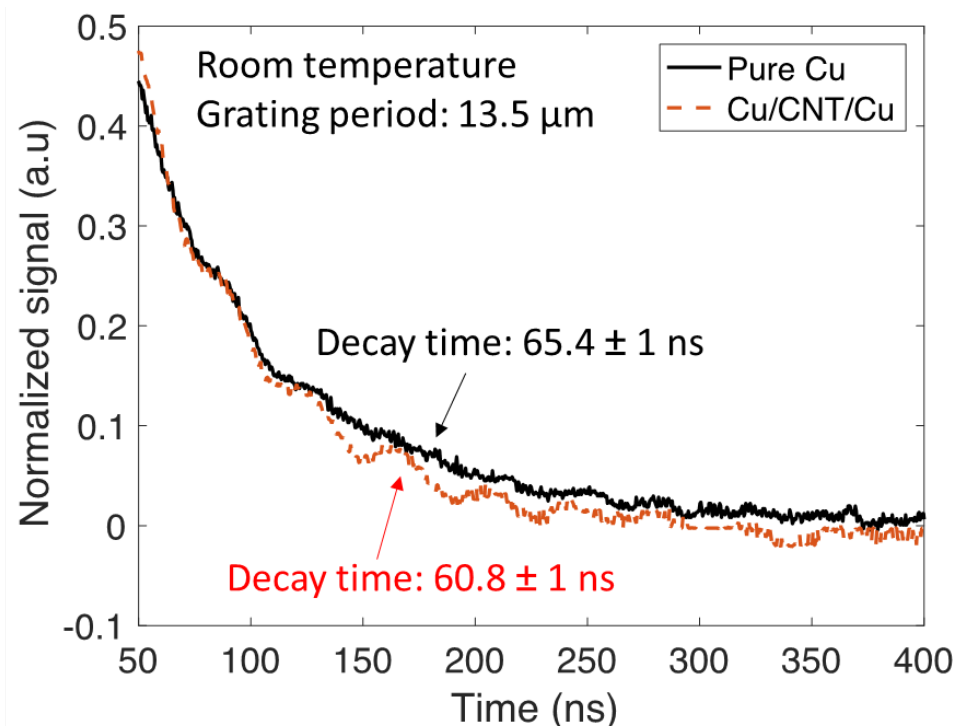
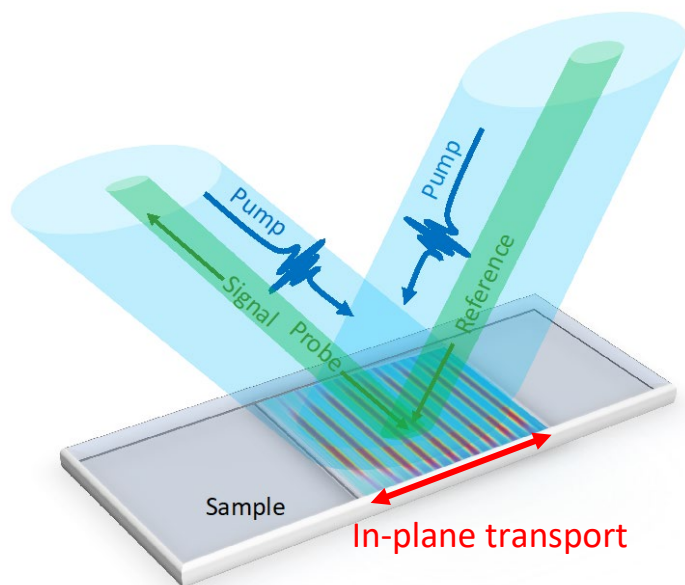


- Decreased resistivity ~5 % for electrospun Cu/CNT/Cu prototype samples has been realized
- Higher resistivity for printed samples ➡ organic solvent & surfactant are not effectively removed

- Graphitic structure visible in the bright field image
➡ supports alignment of CNTs parallel to the Cu surface
- Uniform & dense Cu matrix on electrospun CNT layer

Technical Accomplishments – FY19

Established Transient Thermal Grating technique (TTG) & analyzed influence of CNT interface on the in-plane thermal transport properties

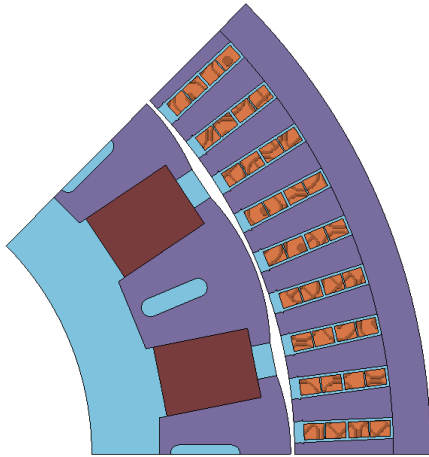


- TTG is a pump-probe technique that monitors the cooling of the material to a grating heating pattern on the surface of the sample. The change in optical properties is linearly related to the temperature changes of the surface
- Decrease in thermal decay time compared Cu reference indicates higher thermal conductivity in Cu/CNT/Cu
- Persisted oscillations in Cu/CNT/Cu sample suggests potential ballistic phonon transport in CNTs

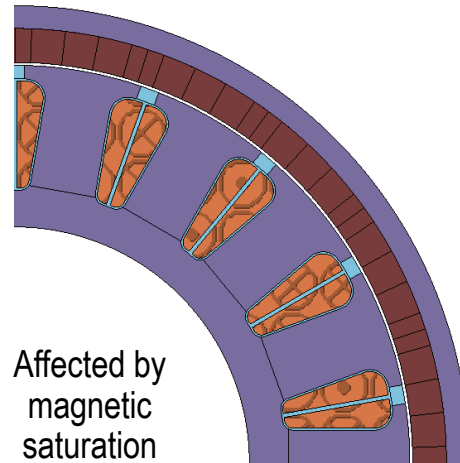
Technical Accomplishments – FY19

Analyzed impact of UCC winding conductivity on various traction motor topologies

Inner-Rotor Spoke
Internal PM motor



Outer-Rotor
Surface PM motor

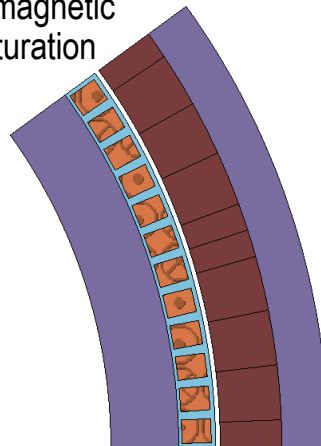


Affected by
magnetic
saturation

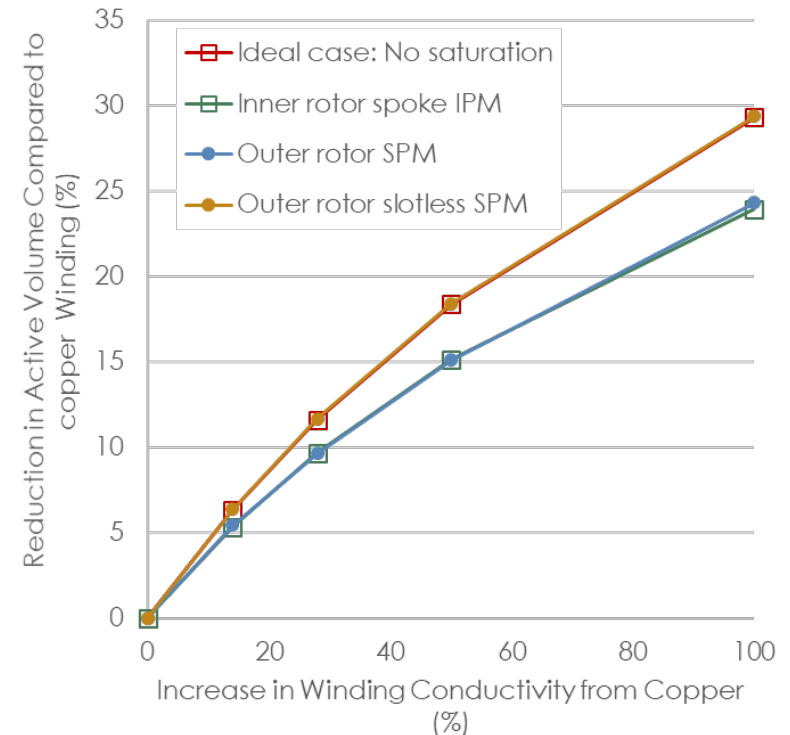
Calculations assumed:

- Three topologies of heavy rare-earth-free permanent magnet (PM) motors
- Same outer diameter of 242 mm & 100 kW peak power
- The conductivity of the winding is varied up to 2X of the Cu & the heat load in the slots are kept constant

No magnetic
saturation



Outer-Rotor Slotless
Surface PM motor



With 30% increase in conductivity:

- 10% reduction in volume for conventional motors
- 12% reduction for motors not affected by magnetic saturation (slotless)

Please see:
Project ID: elt212
Non-Heavy Rare-Earth High-Speed Motor
T. Raminosa, ORNL, June 11

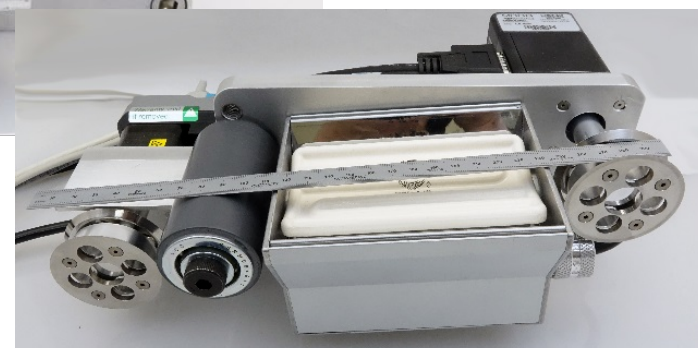
Technical Accomplishments – FY19

Designed & assembled a compact tape handler system for roll-to-roll multi-coat CNT deposition on 0.50" wide & up to 25' long Cu tape using sonospray

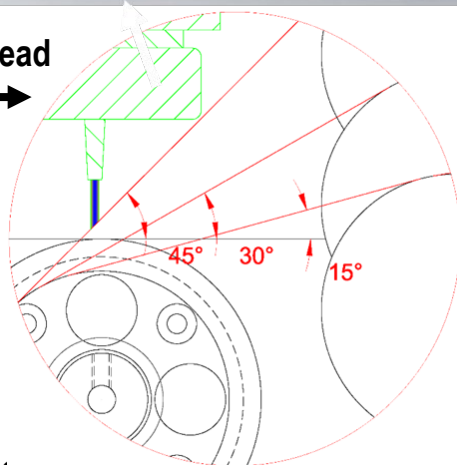


Long-length
prototyping will
begin in May

Top view



Spray head



- To facilitate CNT alignment, the spray angle can be varied by adjusting the idler spool
- The radiant heater continuously cures the CNT coating & enables multi-coat deposition
- The tape speed can be varied from 0.5 mm/sec to 100 mm/sec

Collaboration and Coordination with Other Institutions

Initiated discussions with Southwire, Magnekon, Magna International



Chasm Advanced Materials, Inc: Supplier of CNTs



Southwire: Discussions on performance evaluations & technology integration



Magnekon: Discussions on performance evaluations & technology integration

Remaining Challenges and Barriers for FY19

- Achieving similar performance characteristics from double-wall & multi-wall CNTs compared to single-wall based Cu/CNT/Cu composites
- Effects of additional Cu/CNT layers on the electrical performance of the multilayered UCC prototypes
- Solution for large parameter space involved in producing UCC tapes
- Achieving similar performance on UCC prototypes using long-length deposition system

Proposed Future Work

Remainder of FY19:

- Continue process optimization efforts for the production of UCCs
- Continue integration & optimization of additional Cu/CNT stack(s) on the first Cu/CNT/Cu architecture.
- Analyze electrical & thermal impacts of additional Cu/CNT layers
- Produce prototypes using newly established long-length scalable CNT deposition capability

FY20:

- Continue processing, optimization, characterization efforts & fabricate prototypes
- Continue incorporating detailed theoretical modelling efforts to support/speed-up experimental work
- Perform comprehensive properties evaluation of samples produced by long-length CNT deposition system (alignment, morphology, electrical, thermal)

Any proposed future work is subject to change based on funding levels

Summary

- **Relevance:** Advanced materials with higher electrical conductivity are needed to increase power density & reduce cost while improving performance & reliability of electric motors
- **Approach:** Design an advanced conductor with reduced electrical loss by depositing CNTs on Cu tapes
- **Collaborations:** Chasm, Southwire, and Magnekon
- **Technical Accomplishments:**
 - Continued processing, optimization, characterization efforts & fabricate prototypes
 - Explored viability of two new scalable processing techniques for CNT deposition – electrospinning & aerosol jet printing
 - Conducted microstructural analyses to provide key insights into process optimization
 - Demonstrated that theoretical modeling can support experimental efforts
 - Analyzed influence of CNT interface on the in-plane thermal transport properties
 - Integrated additional Cu/CNT layers on the first Cu/CNT/Cu architecture, performed electrical characterizations, demonstrated improved conductivity over reference pure Cu
 - Analyzed the impact of UCC winding conductivity for various traction motor topologies
- **Future Work:** Continue processing, optimization, characterization efforts, & fabricate multilayered as well as long-length processed prototypes; incorporate detailed theoretical modelling efforts to support/speed-up experimental work; & analyze electrical & thermal impacts of additional Cu/CNT layers